

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	16649	(PR or P/R or photoresist or resist or photomask or photo-mask) near8 (electrode or pad or contact) near8 (opening or via or hole or space)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:07
L3	1087	1 same (dam or wall or perimeter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:09
L4	77	3 same (solder or resin or ball or bond)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:09
L5	56	4 and ((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:10

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	165	solder adj resist adj mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:37
L2	73392	dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:35
L3	7	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:35
L4	6197	solder adj mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:37
L5	265	2 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:37
L6	10	("5310574").URPN.	USPAT	OR	ON	2006/02/02 17:41
L7	20	("5395040").URPN.	USPAT	OR	ON	2006/02/02 17:44
L8	9952	solder adj resist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:45
L9	301	2 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:45

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L1	16649	(PR or P/R or photoresist or resist or photomask or photo-mask) near8 (electrode or pad or contact) near8 (opening or via or hole or space)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:07
L3	1087	1 same (dam or wall or perimeter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:09
L4	77	3 same (solder or resin or ball or bond)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:09
L5	56	4 and ((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01
L6	165	(solder adj resist adj mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01
L7	73392	dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01
L8	7	6 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01
L9	6197	solder adj mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01

L10	265	7 and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01
L11	9952	solder adj resist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:02
L12	301	7 and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:02
L13	4645035	(substrate or wafer or carrier or board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30
L14	2562505	(electrode or pad or trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30
L15	2792601	(solder\$6 or bump or ball or bond\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30
L16	142263	(dam or wall or block) near8 L14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30
L17	3615	L16 same L13 same L15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30

L18	6420	((438/612) or (438/613) or (438/614) or (438/652) or (438/686)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 18:30
L19	123	L17 and L18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30
L20	107	L19 and ((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30